



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814  
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.

Serial No.: 10/767,439

Filing date: January 30, 2004

For: PROCESS OF PRODUCING  
SEMICONDUCTOR CHIP WITH SURFACE  
INTERCONNECTION AT BUMP (as amended)

Atty. ref.: AI 318 D1

**AMENDMENT  
AFTER  
FINAL REJECTION**

September 10, 2007

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is responsive to the Office Action of June 11, 2007, the period for reply to which has been set to expire on September 11, 2007.

A fee of \$None is also being submitted concurrently. Should this remittance be accidentally missing, however, or should any additional fees be needed, the Director may charge such fees to our Deposit Account number 18-0002.

Please amend above-identified application as specified on the following pages, and then reconsider the application in view of the Remarks that are presented thereafter.